

## I) IC Lab Schedule (2009 January PRISM)

DATE	LAB	DESCRIPTION
January 15	1	Lab tour; Safety discussion; Determining charge carrier type; Determining resistivity.
January 16	2	Wafer clean; Wet oxidation.
January 19	3	Photolithography Level 1; Oxide etch; Strip resist; Wafer clean; Spin on dopant glass.
January 20	4	Diffuse; Etch dopant glass; Demonstrate diode electrical characteristics.
January 21	5	Photolithography Level 2; Oxide etch; Strip resist; Wafer clean; Gate oxidation
January 22	6	Photolithography Level 3; Oxide etch; Strip resist; Photolithography Level 4.
January 23	7	Evaporate aluminum; Lift-off; Sinter & Anneal; Solder to glass slide
January 26	8	Measurement Experiments 1-6.
January 27	9	Measurement Experiments 1-6.
January 28	10	Measurement Experiments 1-6.
January 29	11	Measurement Experiments 1-6.
January 30	12	Measurement Experiments 1-6.